X-ray TDI camera C12200 series

High speed readout

High Resolution

High Sensitivity

Evolutional high speed scanning with TDI technology

High speed readout 36.8 m/min.





X-ray TDI camera C12200 Series is useful for in-line applications requiring high-speed operation with high sensitivity. TDI imaging is appropriate for applications where it is desired to record a linear movement, or where the aspect ratio of the subject being imaged is significantly asymmetric. Low brightness under high resolution usage, a problem with conventional line sensor cameras, is improved with this X-ray TDI camera, making it suitable for applications which require high resolution.

Printed circuit board (PCB) inspection

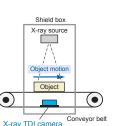
Surface-mounted component inspection

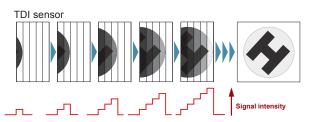
Battery inspection

High-resolution in-line non-destructive inspection

TDI technology

Time Delay Integration is a technology of scanning in which a frame transfer device produces a continuous video image of a moving object by means of a stack of linear arrays aligned with and synchronized to the motion of the object to be imaged in such a way that, as the image moves from one line to the next, the integrated charge moves along with it, providing higher resolution at lower light levels than is possible with a line-scan camera.



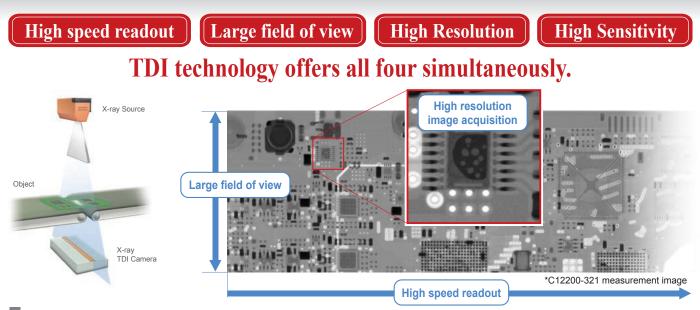


Features

- High S/N ratio with 12 bit (-321) /16 bit (-461) output
- Camera Link interface (Base configuration)
- Single power supply (+15 V) operation
- Real time dark current / shading correction function
- Frame readout mode for easy installation alignment



High-resolution, High-speed Camera with a Large Field of View for In-line 100 % X-ray Inspection

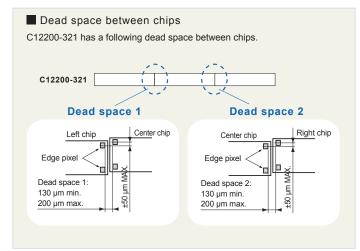


SPECIFICATIONS

Type number		C12200-321	C12200-461
Scintillator		Csl Scintillator	
Window		FOS (Fiber optic plate with scintillator)	
Effective X-ray tube voltage range		Approx. 25 kV to 90 kV *1	
CCD pixel size		48 μm × 48 μm	
Number of pixels		4608 (H) × 110 (V)	6144 (H) × 110 (V) * ²
X-ray sensitive area		221.1 mm (H) × 5.2 mm (V)	293.4 mm (H) × 5.2 mm (V)
Line speed		2.88 m/min to 23.04 m/min	
TDI line rate	1×1	Max. 8.0 kHz (23.04 m/min)	
	Binning 2 × 2	Max. 6.4 kHz (36.864 m/min)	
CCD pixel clock		5.0 MHz	
A/D converter		12 bit	16 bit
Digital interface		Camera Link	
Interface (Camera Link)		Base Configuration	
Pixel clock (Camera Link)		40 MHz	50 MHz
Output signals (Image data)		12 bit digital output	16 bit digital output
Power supply		DC +15 V	
Power consumption		Approx. 40 VA	

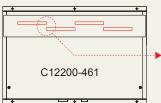
*1 Usable range of X-ray strength may vary depending on the tube current, the tube voltage and the distance

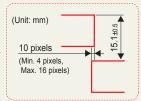
*2 "Active CCD pixel number" is all outputting pixel number including overlapped pixel. When the overlapped pixels are deleted, actual pixel numbers will vary. And also, X-ray sensitive area will vary.



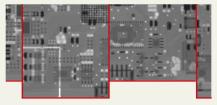
Wide detection width with no dead areas.

C12200-461 offers a wide detection area with no dead areas due to its staggered sensors.



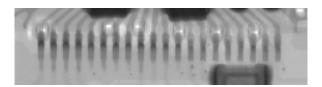


Overlapped type measurement example

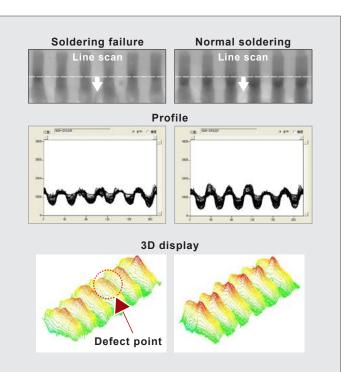


MEASUREMENT EXAMPLES

Inspection of a solder's back fillet



If the back fillet of the solder on a PCB has a defect, a connection error will occur even with small vibrations. For observation of the back fillet part, X-ray transmission technique has been applied but only with an off-line system. Our X-ray TDI camera realizes in-line inspection because it can acquire high speed profile data with high sensitivity. 3D brightness level can be displayed using software.

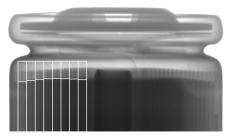


Lithium-ion battery inspection

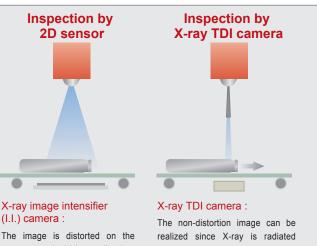
In case of 2D sensor, the dimensional measurement cannot be implemented correctly because the image is distorted on the corner areas of the X-ray irradiation. The long length sample needs to be located on center of X-ray source, so the sample has to be relocated each time. X-ray TDI camera can capture the image with no distortion by line scan method, so it is not necessary to relocate the samples and it enables the continuous inspection for long length object without stopping.



Not necessary to relocate the samples and possible to inspect the long length object with no distortion.



Possible to inspect the mismatch of rolling and measure the length of electrode with no distortion.



(I.I.) camera :

corner areas in thickness direction, and the dimensional measurement cannot be implemented correctly.





vertically to the object and the dimensional measurement can be implemented correctly.

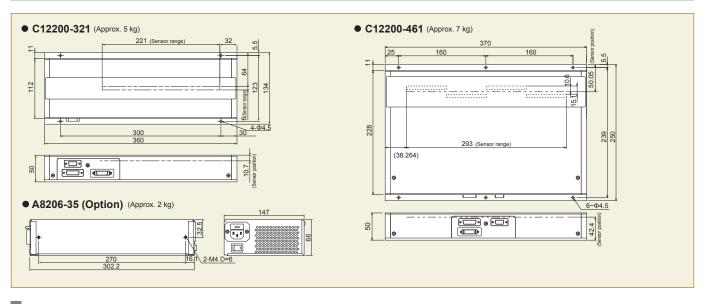


Short of the solution Condition of the connection on electrode

Void inspection of BGAs (Ball Grid array) X-ray TDI camera Line sensor reduced 000000 X-rav irradiation area Object 00000 X-ray light Moving direction X-ray TDI camera can inspect the samples easily by high source speed scan with narrow irradiate area. X-ray TDI camera can reduce the X-ray irradiation S/N ratio is one of advantage and low X-ray radiation is on the sample dramatically by high speed with enough to inspect the void existence. narrow irradiation area. So it can reduce the risks Furthermore it contribute to make a smaller size of system to break down the ICs on the PC.

DIMENSIONAL OUTLINES (Unit: mm)

by reducing a lot of X-ray irradiation.



OPTIONS

- Power supply unit : A8206-35
- Power cable 5 m : A10847-05
- Software API Support (Microsoft Windows) : DCAM-API (http://www.dcamapi.com)

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